

L Number	Hits	Search Text	DB	Time stamp
3	42	(molding with cavity) and (air adj vent) and (semiconductor adj package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 09:08
4	586	(encapsula\$) and (air adj vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 07:23
5	101	(encapsula\$) and (air adj vent) and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 07:46
6	51	(encapsula\$) and (air adj vent) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 07:49
7	158	(encapsula\$) and (air adj vent) and recesses	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 07:49
8	197	(molding with cavity) and (air adj vent) and recesses	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:42
9	281	257/795.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:57
10	2	257/795.ccls. and (air adj vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:43
11	3379	257/787.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:47
12	45	257/787.ccls. and (air adj vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:47
13	403	257/789.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:57
14	3	257/789.ccls. and (air adj vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:57
15	117	(molding adj cavity) and (air adj vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 09:13
16	287	(molding adj cavity) with recesses	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 09:14

-	814	(molding with cavity) and (air adj vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 08:31
-	108	(molding with cavity) and (air adj vent) and 257/\$.ccls.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/08 16:56
-	121	(molding with cavity) and (air adj vent) and encapsula\$	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/08 16:56